## In the Claims

Claim 1 (Currently amended): A resistor comprising:

an insulating substrate having first and second opposite flat surfaces and having a shape and a composition;

a first resistive foil having a low TCR of 0.1 to 1 ppm/°C and a thickness of 0.03 mils to about 0.7 mils cemented to the first flat surface with a cement;

~~the first resistive foil having a pattern to produce a desired resistance value;~~

a second resistive foil having a low TCR of 0.1 to 1 ppm/°C and a thickness of 0.03 mils to 0.7 mils cemented to the second flat surface, the second resistive foil connected to the first resistive foil, the first resistive foil and second resistive foil having approximately equal resistance values and providing approximately equal power dissipation on both surfaces of the substrate thereby reducing temperature gradients across the substrate, preventing bending of the insulating substrate, and avoiding resistance change associated with bending;

the insulating substrate having a modulus of elasticity of $10 \times 10^6$ psi to $100 \times 10^6$ psi and a thickness of 0.5 mils to 200 mils;

the first and second resistive foil each having a pattern to produce a desired resistance value;

the ~~first resistive foil, pattern, and~~ insulating substrate, the first resistive foil, the second resistive foil and each pattern being selected to provide a cumulative effect of reduction of resistance change due to power.

Claim 2 (Previously presented): The resistor of claim 1 wherein the shape of the insulating substrate is selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 3 (Previously presented): The resistor of claim 1 wherein the composition of the insulating substrate is selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 4 (Previously presented): The resistor of claim 1 wherein the thickness of the insulating substrate is selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 5 (Currently amended): The resistor of claim 1 wherein the TCR of the first resistive foil and the TCR of the second resistive foil are ~~is~~ selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 6 (Currently amended): The resistor of claim 5 wherein each of the first and second resistive ~~foil~~ foils is etched to form longitudinal and transverse strands in ~~a pattern~~ patterns selected to reduce bending and provide the cumulative effect of reduction of resistance change due to applied power.

Claim 7 (Original): The resistor of claim 1 wherein the cement is selected to provide the cumulative to reduce the effect of resistance change due to power.

Claim 8 (Original): The resistor of claim 6 wherein the heat transmissivity of the cement is selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 9 (Original): The resistor of claim 6 wherein the thickness of the cement is selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 10 (Cancelled).

Claim 11 (Previously presented): The resistor of claim 1 wherein the TCR is determined for a temperature range from 25°C to 125°C.

Claim 12 (Currently amended): The resistor of claim 1 wherein the first and second resistive foil, each pattern, and the insulating substrate are selected to provide the cumulative

effect of reduction of resistance change due to power by offsetting change in resistance due to temperature changes in ~~the first resistive foil~~ the first and second resistive foils with change in resistance due to stress after cementing the first and second resistive ~~foil~~ foils to the substrate.

Claim 13 (Previously presented): The resistor of claim 1 wherein an operating temperature for the resistor is greater than ambient temperature.

Claim 14 (Currently amended): A power resistor, comprising:

an insulating substrate having first and second opposite flat surfaces and having a shape and a composition;

a first resistive foil having a low TCR of 0.1 to 1 ppm/°C and a thickness of 0.03 mils to about 0.7 mils cemented to the first flat surface with a cement;

~~the first resistive foil having a pattern to produce a desired resistance value;~~

a second resistive foil having a low TCR of 0.1 to 1 ppm/°C and a thickness of 0.03 mils to 0.7 mils cemented to the second flat surface, the second resistive foil connected to the first resistive foil, the first resistive foil and second resistive foil having approximately equal resistance values and providing approximately equal power dissipation on both surfaces of the substrate thereby reducing temperature gradients across the substrate, preventing bending of the insulating substrate, and avoiding resistance change associated with bending;

the insulating substrate having a modulus of elasticity of $10 \times 10^6$ psi to $100 \times 10^6$ psi and a thickness of 0.5 mils to 200 mils;

the first resistive foil, ~~pattern~~the second resistive foil, and insulating substrate being selected to provide a cumulative effect of reduction of resistance change due to power; and

wherein the shape of the insulating substrate, the composition of the insulating substrate, and the TCR of the first resistive foil are selected to provide the cumulative effect of reduction of resistance change due to power.

Claim 15 (Cancelled).

Claim 16 (New): A resistor comprising:

a substrate having first and second opposite flat surfaces;

first and second resistive foils;

a first adhesive attaching the first resistive foil to the first flat surface of the substrate;

a second adhesive attaching the second resistive foil to the second opposite flat surface of the substrate;

the first and second resistive foils being connected to one another;

the resistive values and the TCR's of the first and second resistive foils being chosen so that when power is applied to the first and second resistive foils the first resistive foil is heated equally with the second resistive foil.

Claim 17 (New): The resistor of claim 16 wherein the TCR's of the first and second resistive foils are between 0.1 and 1 ppm/degree C.